



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DB2X60300L

Silicon epitaxial planar type

For high speed switching circuits
 DB3X603K in Mini2 type package

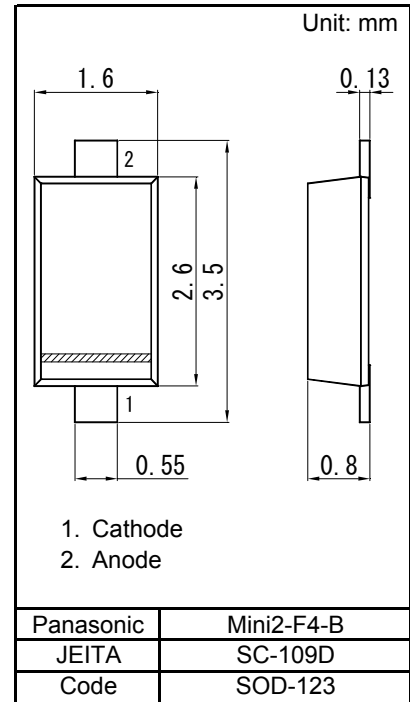
■ Features

- High reverse voltage VR
- Small reverse current IR
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: A9

■ Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

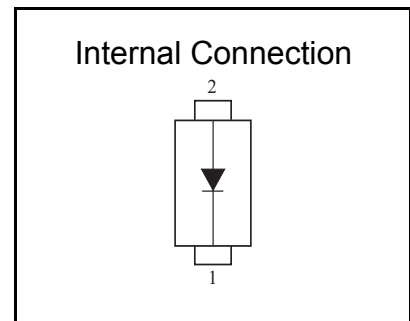


■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	60	V
Maximum peak reverse voltage	VRM	60	V
Forward current (Average) *1	IF(AV)	500	mA
Non-repetitive peak forward surge current *2	IFSM	2	A
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note: *1 TI = 80°C

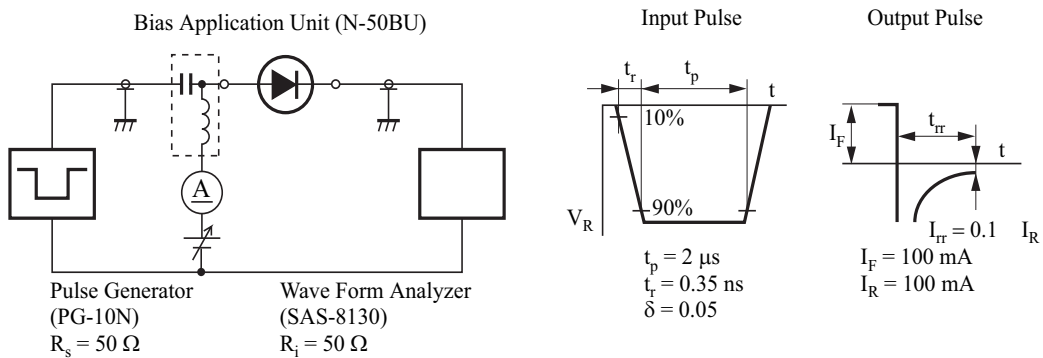
*2 50 Hz sine wave 1 cycle (Non-repetitive peak current)



■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

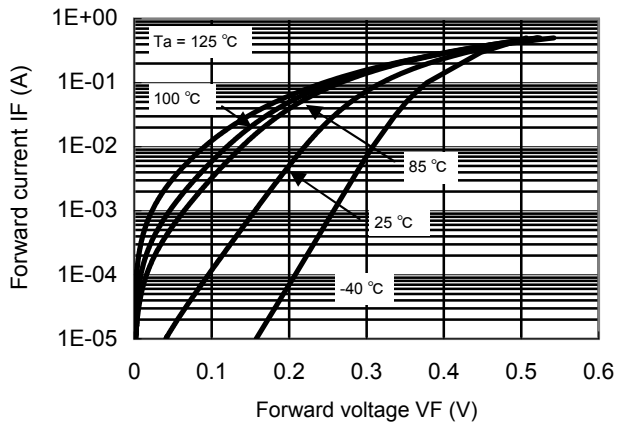
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 500 mA			0.65	V
Reverse current	IR	VR = 50 V			100	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		14		pF
Reverse recovery time *1	trr	IF = IR = 100 mA, Irr = 0.1 \times IR		4.5		ns

- Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 2. Schottky diode is frail with static electricity, and it should be kept in safety from shock of static electricity and static electricity level.
 3. Absolute frequency of input and output is 1 000 MHz.
 4. *1 : trr measurement circuit

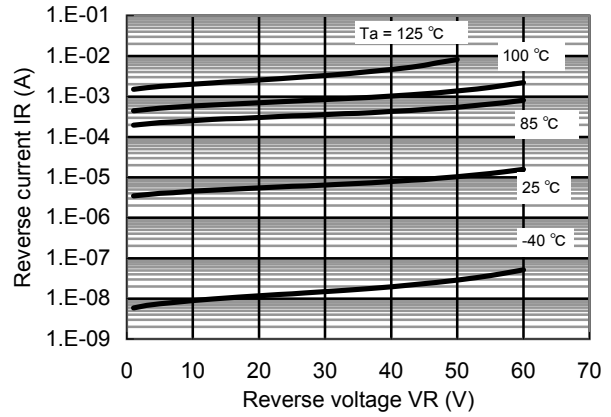


Technical Data (reference)

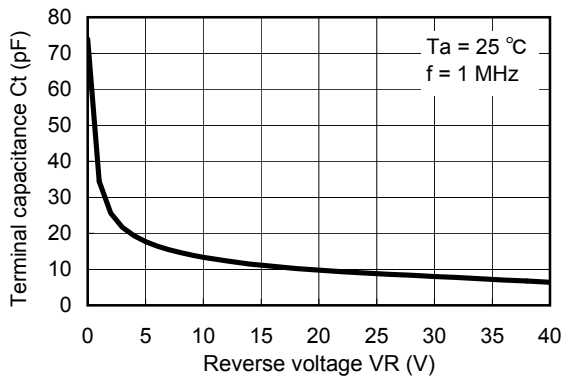
IF - VF



IR - VR

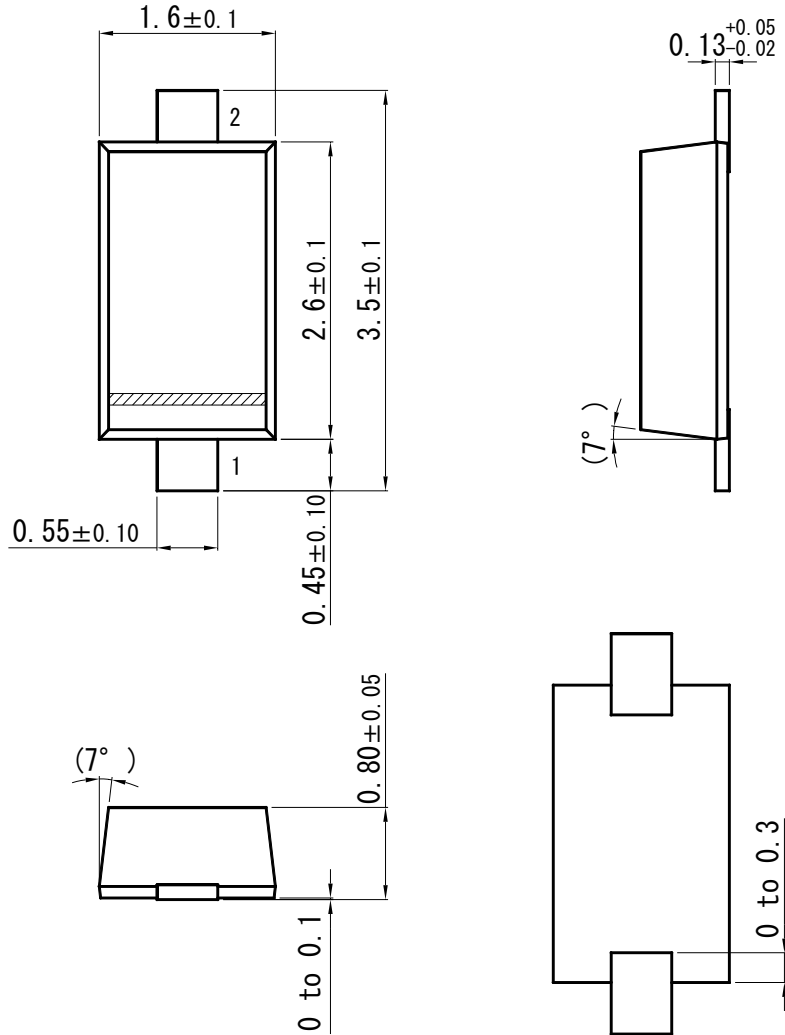


Ct - VR

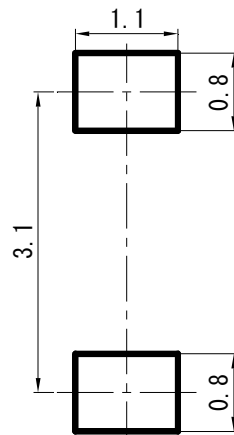


Mini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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